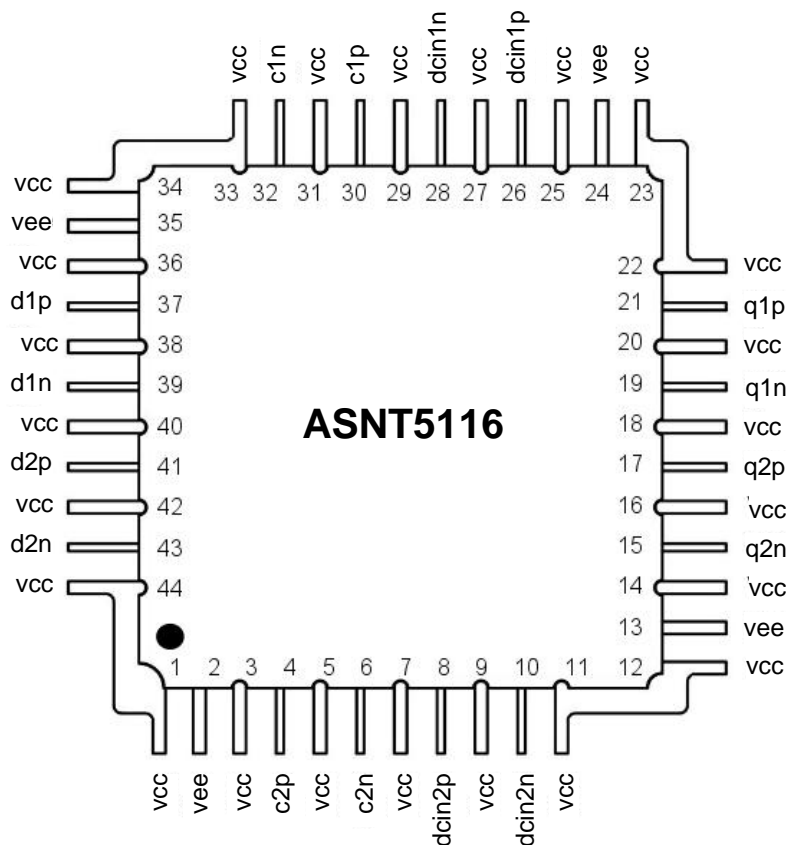# ASNT5116-KMM
DC-32*Gbps* Linearized High Sensitivity Dual D-Type Flip-Flop

- High speed broadband 2-channel D-Type Flip-Flop for data retiming with full rate clock

- Sensitive input data buffer with increased CM range that is ideal for sampling applications

- Input data single-ended common mode controls

- Exhibits low jitter and limited temperature variation over industrial temperature range

- 4*ps* set-up/hold time capability

- 88% clock phase margin for retiming of data input eye

- Fully differential CML input interfaces

- Fully differential CML output interface with 400*mV* single-ended swing

- Single +3.3*V* or -3.3*V* power supply

- Power consumption: 1.01*W*

- Fabricated in SiGe for high performance, yield, and reliability
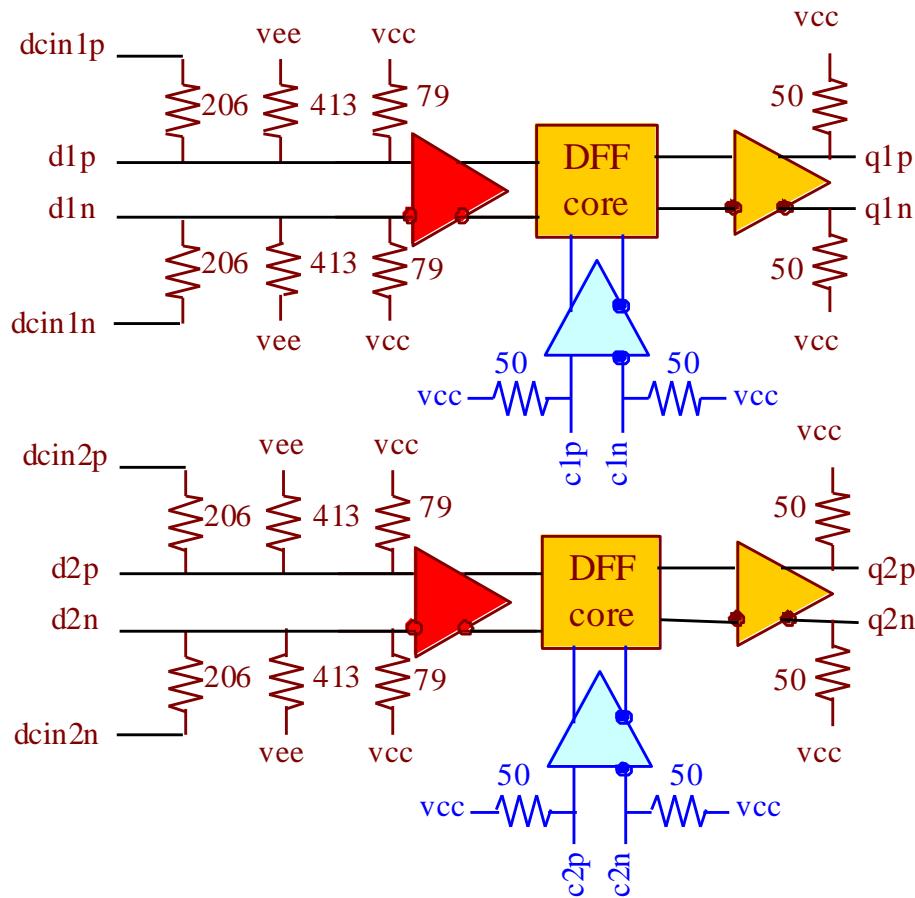
- Custom CQFP 44-pin package

DESCRIPTION

Fig. 1. Functional Block Diagram

The temperature stable ASNT5116-KMM SiGe IC provides broadband data retiming functionality and is intended for use in high-speed measurement / test equipment. The IC shown in Fig. 1 can sample up to 32*Gbps* data signals d1p/d1n and d2p/d2n with up to 32*GHz* clock sources c1p/c1n and c2p/c2n to create 32*Gbps* retimed NRZ data outputs q1p/q1n and q2p/q2n. The data input buffers are designed to have increased input signal sensitivity and are able to operate over a wider range of input common mode (CM) voltages. The actual common mode voltage levels on data inputs d1p/d1n and d2p/d2n can be adjusted by applying voltages between vee and vcc to the corresponding control inputs dcin1p/dcin1n and dcin2p/dcin2n. The part's I/O's support the CML logic interface with on chip equivalent 50*Ohm* termination and may be used differentially, AC/DC coupled, single-ended, or in any combination (see also POWER SUPPLY CONFIGURATION). In the DC-coupling mode, the input signal's common mode voltage should comply with the specifications shown in ELECTRICAL CHARACTERISTICS. In the AC-coupling mode, the input termination provides the required common mode voltage automatically. The differential DC signaling mode is recommended for optimal performance.

It should be noted that control inputs dcin1p/dcin1n and dcin2p/dcin2n should be always connected to voltage sources to ensure correct 50*Ohm* terminations for the data inputs.

POWER SUPPLY CONFIGURATION

The part can operate with either a positive supply (vcc = 0.0V=ground and vee = -3.3V), or a negative supply (vcc = +3.3V and vee = 0.0V=ground). In case of a positive supply, all I/Os need AC termination when connected to any devices with 50Ohm termination to ground. Different PCB layouts will be needed for each different power supply combination.

All the characteristics detailed below assume vcc = 0.0V and vee = -3.3V.

ABSOLUTE MAXIMUM RATINGS

Caution: Exceeding the absolute maximum ratings shown in Table 1 may cause damage to this product and/or lead to reduced reliability. Functional performance is specified over the recommended operating conditions for power supply and temperature only. AC and DC device characteristics at or beyond the absolute maximum ratings are not assumed or implied. All min and max voltage limits are referenced to ground (assumed vcc).

Table 1. Absolute Maximum Ratings

Parameter	Min	Max	Units
Supply Voltage (vee)		-3.6	*V*
Power Consumption		1.2	*W*
Input Data Voltage Swing (SE)		1.7	*V*
Input Clk Voltage Swing (SE)		1.7	*V*
Case Temperature		+90	*ºC*
Storage Temperature	-40	+100	*ºC*
Operational Humidity	10	98	*%*
Storage Humidity	10	98	*%*

TERMINAL FUNCTIONS

TERMINAL			DESCRIPTION
Name	**No.**	**Type**	
High-Speed I/Os			
d1p	37	CML Input	Differential data inputs with internal SE $50Ohm$ termination to vcc
d1n	39		
d2p	41		
d2n	43		
c1p	30	CML Input	Differential clock inputs with internal SE $50Ohm$ termination to vcc
c1n	32		
c2p	4		
c2n	6		
q1p	21	CML Output	Differential data outputs with internal SE $50Ohm$ termination to vcc. Require external SE $50Ohm$ termination to vcc
q1n	19		
q2p	17		
q2n	15		
DC Controls			
dcin1p	26	Input	Input data DC common mode voltage level controls. **Should be always connected to voltage sources!**
dcin1n	28		
dcin2p	8		
dcin2n	10		
Supply and Termination Voltages			
Name	**Description**		**Pin Number**
vcc	Positive power supply (+3.3*V* or 0*V*)		1, 3, 5, 7, 9, 11, 12, 14, 16, 18, 20, 22, 23, 25, 27, 29, 31, 33, 34, 36, 38, 40, 42, 44
vee	Negative power supply (0*V* or -3.3*V*)		2, 13, 24, 35

ELECTRICAL CHARACTERISTICS

PARAMETER	MIN	TYP	MAX	UNIT	COMMENTS
General Parameters					
vcc		0.0		*V*	External ground
vee	-3.47	-3.3	-3.14	*V*	±5%
*I*vcc		305	325	*mA*	
Power consumption		1.01	1.07	*W*	
Junction temperature	-25	50	125	*°C*	
HS Input Data (d1p/d1n, d2p/d2n)					
Data rate	0.0	32	40	*Gbps*	
Swing	0.01		1.6	*V*	Differential or SE, p-p
CM Voltage Level	vcc-0.7+sw/2	vcc+0.6-sw/2		*V*	Must match for both inputs
HS Input Clock (c1p/c1n, c2p/c2n)					
Frequency	0.0	32	40	*GHz*	
Swing	0.05		1.3	*V*	Differential or SE, p-p
CM Voltage Level	vcc-0.7+sw/2	vcc+0.6-sw/2		*V*	Must match for both inputs
Duty Cycle	40	50	60	*%*	
Clock phase margin	86	88	90	*%*	For reliable data latching
HS Output Data (q1p/q1n, q2p/q2n)					
Data rate	0.0	32	40	*Gbps*	
Logic "1" level	vcc-0.05	vcc-0.03	vcc-0.01	*V*	
Logic "0" level	vcc-0.46	vcc-0.44	vcc-0.42	*V*	With external 50*Ohm* DC termination
Jitter		0.15		*ps*	Peak-to-peak at 32*Gbps*
DC Input Controls (dcin1p/dcin1n, dcin2p/dcin2n)					
Max level		vcc + 1.0		*V*	
Min level		vcc - 1.0		*V*	

PACKAGE INFORMATION

The chip die is housed in a custom 44-pin CQFP package shown in Fig. 2. The package provides a center heat slug located on its back side to be used for heat dissipation. ADSANTEC recommends for this section to be soldered to the vcc plain, which is ground for a negative supply, or power for a positive supply.

The part's identification label is ASNT5116-KMM. The first 8 characters of the name before the underscore identify the bare die including general circuit family, fabrication technology, specific circuit type, and part version while the 3 characters after the underscore represent the package's manufacturer, type, and pin out count.

This device complies with the Restriction of Hazardous Substances (RoHS) per 2011/65/EU for all ten substances.
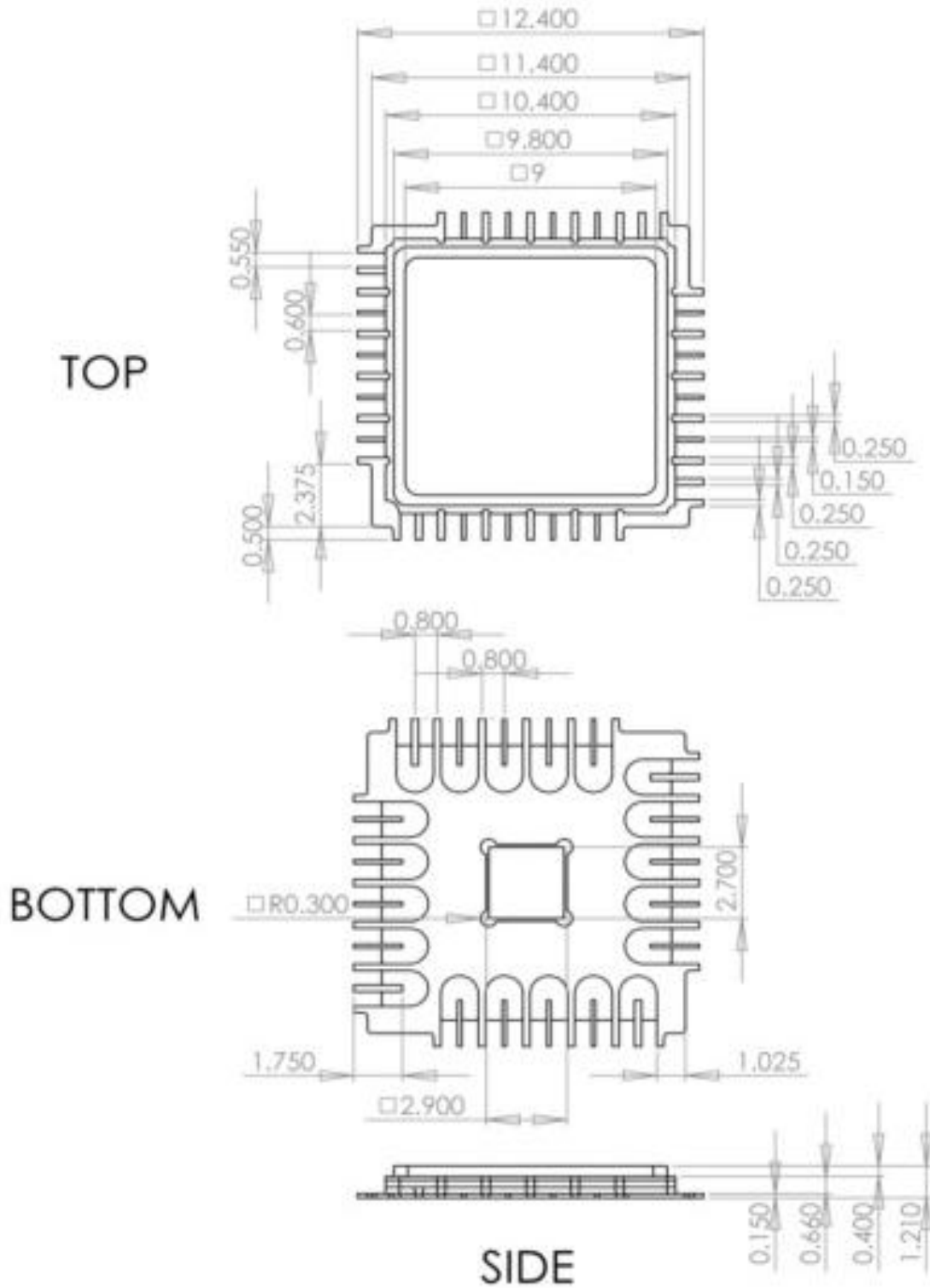
Fig. 2. CQFP 44-Pin Package Drawing (All Dimensions in mm)

REVISION HISTORY

Revision	Date	Changes
1.4.2	05-2020	Updated Package Information
1.3.2	07-2019	Updated Letterhead
1.3.1	01-2014	Corrected title
1.2.1	05-2013	Removed data duty cycle specification
		Corrected terminal functions
1.1.1	05-2013	Corrected pin out diagram
1.0.1	03-2013	First release